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Title:

**TW0455938B: WAFER POLISHING STOP DETECTION METHOD AND POLISHING STOP DETECTION DEVICE**

Country:

TW Taiwan

Kind:

B Patent

Inventor:

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Published // Filed:

Sept. 21, 2001 / Dec. 9, 1999

Application

TW1999088121563

Number:

IPC Code:

H01L 21/304; B24B 37/04;

ECLA Code:

None


Priority Number:

Dec. 10, 1998 [JP1998000368466](#)

Abstract:

A wafer polishing stop detection method and polishing stop detection device which provides the method for detecting CMP polishing stop by polishing surface status index of polishing wafer in more precision. The solution of the wafer polishing stop detection method is irradiating the light from the light source; collecting the reflection on the color recognition sensor using fiber optics for light color component recognition; recognizing the color components of the tracing material on the pre-polished wafer using the color recognition sensor; displaying an "on" status if the color components are recognized and an "off" status if the color components are not recognized; digitally displaying the "on" and "off" periods on the horizontal axis during wafer polishing from a point (except the center) on the rotating wafer surface irradiated by the color recognition sensor; detecting the integral ( $\int S_{gr} dt$ ) for the specified period for "off" pulse width in digital display so that when the detected integral ( $\int S_{gr} dt$ ) can be consistent with the integral value ( $\int S_{gr} dt$ ) for the specified period for "off" pulse width of predetermined best wafer polishing stop, defining it as the wafer polishing stop.

Family:

Buy PDF	Publication	Pub. Date	Filed	Title
	US6342166B1	Jan. 29, 2002		
	US6342166	Jan. 29, 2002	Dec. 6, 1999	Method of detecting end point of p wafer and apparatus for detecting polishing
	TW0455938B	Sept. 21, 2001	Dec. 9, 1999	WAFER POLISHING STOP DETE METHOD AND POLISHING STOP DEVICE
	KR0048040A	July 25, 2000	Dec. 9, 1999	METHOD FOR DETECTING POLI POINT OF WAFER AND APPARA DETECTING THE POLISHING EN
	JP2000183002A2	June 30, 2000	Dec. 10, 1998	METHOD AND DEVICE FOR DET WAFER POLISH END-POINT

5 family members shown above

Other Abstract Info:



DERABS G2000-486551



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